Preferred Devices

Surface Mount Schottky Power Rectifier

Plastic SOD-123 Package

The Schottky Power Rectifier employs the Schottky Barrier principle with a barrier metal that produces optimal forward voltage drop—reverse current tradeoff. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. This package provides an alternative to the leadless 34 MELF style package. These state—of—the—art devices have the following features:

Features

- Guardring for Stress Protection
- Very Low Forward Voltage (0.38 V Max @ 0.5 A, 25°C)
- 125°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Package Designed for Optimal Automated Board Assembly
- Pb-Free Packages are Available

Mechanical Characteristics

- Reel Options: MBR0520LT1 = 3,000 per 7" reel/8 mm tape MBR0520LT3 = 10,000 per 13" reel/8 mm tape
- Polarity Designator: Cathode Band
- Weight: 11.7 mg (approximately)
- Case: Epoxy, Molded
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds



http://onsemi.com

SCHOTTKY BARRIER RECTIFIER 0.5 AMPERES, 20 VOLTS



SOD-123 CASE 425 STYLE 1

MARKING DIAGRAM



B2 = Device Code M = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
MBR0520LT1	SOD-123	3000/Tape & Reel
MBR0520LT1G	SOD-123 (Pb-Free)	3000/Tape & Reel
MBR0520LT3	SOD-123	10,000/Tape & Reel
MBR0520LT3G	SOD-123 (Pb-Free)	10,000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	V
Average Rectified Forward Current (Rated V _R , T _L = 90°C)	I _{F(AV)}	0.5	А
Non–Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	5.5	А
Storage Temperature Range	T _{stg}	-65 to +125	°C
Operating Junction Temperature	TJ	-65 to +125	°C
Voltage Rate of Change (Rated V _R)	dv/dt	1000	V/μs

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

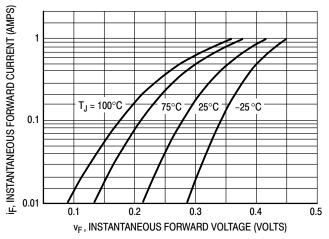
THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance; Junction-to-Ambient (Note 1)	$R_{\theta JA}$	206	°C/W
Thermal Resistance; Junction-to-AmbientLead	$R_{ heta JL}$	150	°C/W

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 2)	٧ _F	$T_J = 25^{\circ}C$	T _J = 100°C	V
(i _F = 0.1 Amps) (i _F = 0.5 Amps)		0.300 0.385	0.220 0.330	
Maximum Instantaneous Reverse Current (Note 2)	I _R	T _J = 25°C	T _J = 100°C	mA
(V _R = 10 V) (Rated dc Voltage = 20 V)		75 μΑ 250 μΑ	5 mA 8 mA	

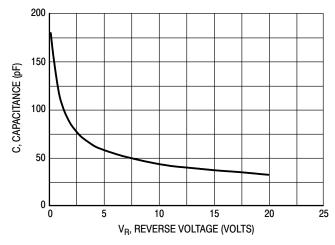
^{1. 1} inch square pad size (1 x 0.5 inch for each lead) on FR4 board. 2. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2%.



10,000 T_J = 100°C 1000 5 10 15 20 28 V_R, REVERSE VOLTAGE (VOLTS)

Figure 1. Typical Forward Voltage

Figure 2. Typical Reverse Current



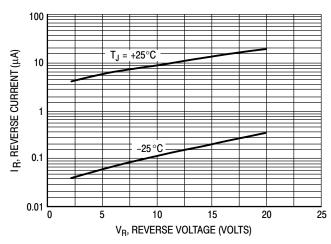
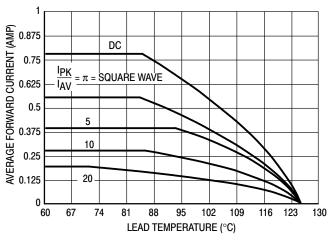


Figure 3. Typical Capacitance

Figure 4. Typical Reverse Current



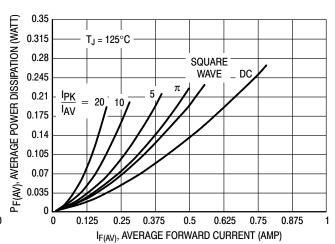
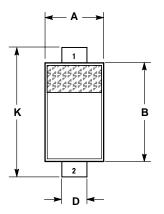


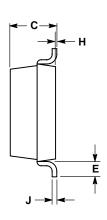
Figure 5. Current Derating (Lead)

Figure 6. Power Dissipation

PACKAGE DIMENSIONS

SOD-123 PLASTIC CASE 425-04 ISSUE C





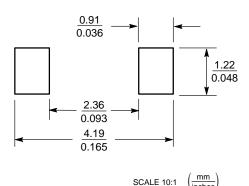
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M. 1982.
- 2. CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.055	0.071	1.40	1.80
В	0.100	0.112	2.55	2.85
С	0.037	0.053	0.95	1.35
D	0.020	0.028	0.50	0.70
Е	0.004		0.25	
Н	0.000	0.004	0.00	0.10
J		0.006		0.15
K	0.140	0.152	3.55	3.85

STYLE 1: PIN 1. CATHODE 2. ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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